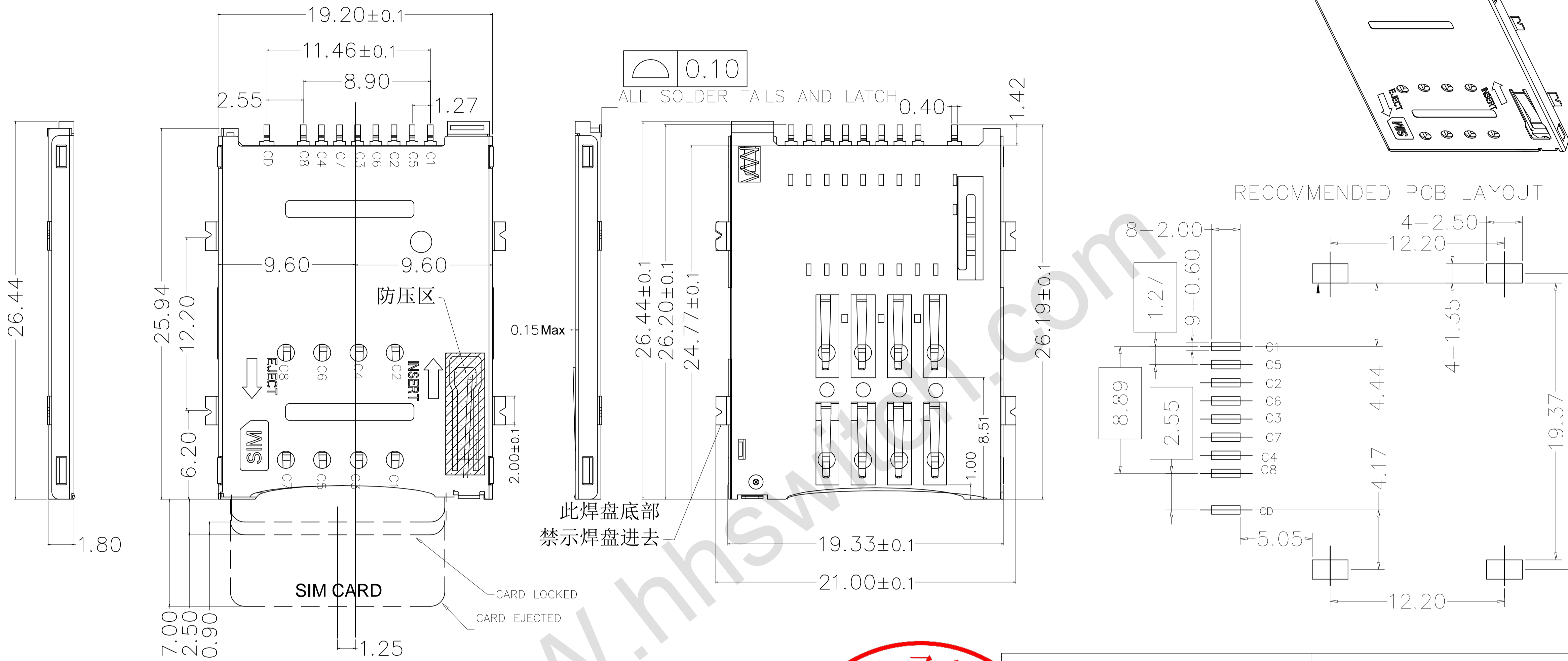
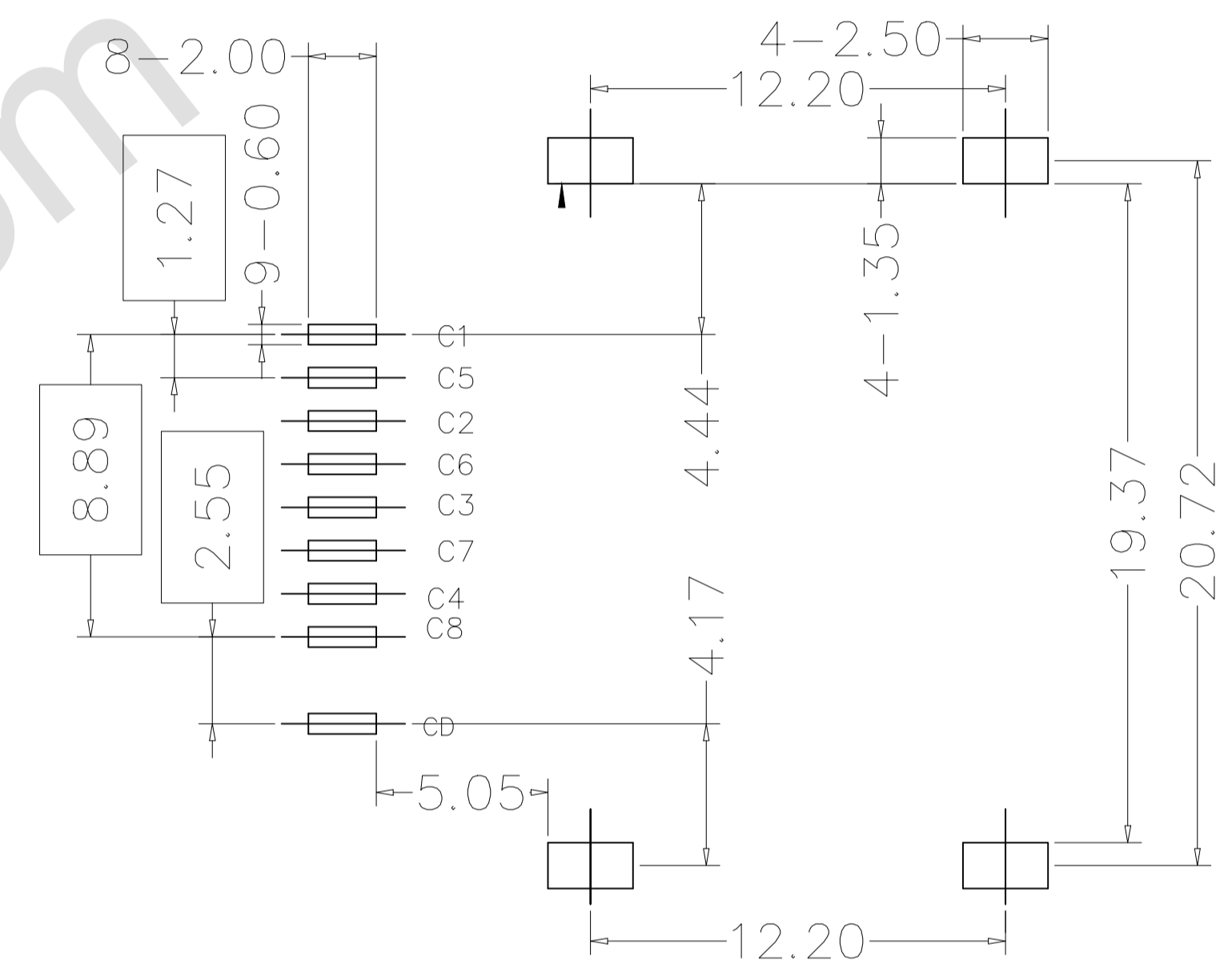


贴片时正反贴须告知，正反贴生产工艺有区别

* 所有原料材质, 生产制程, 电镀必须符合ROHS要求



RECOMMENDED PCB LAYOUT



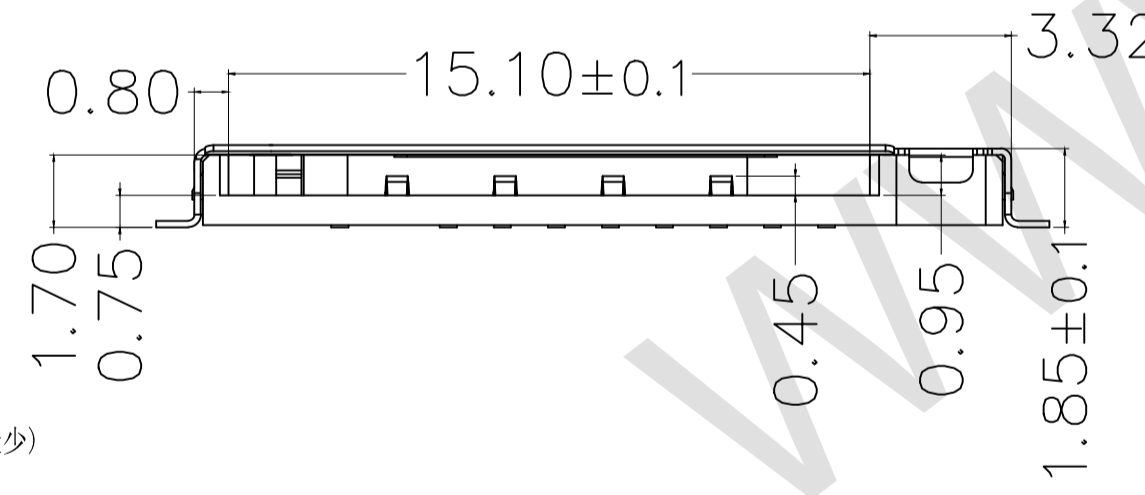
此焊盘底部
禁止焊盘进去

Specification

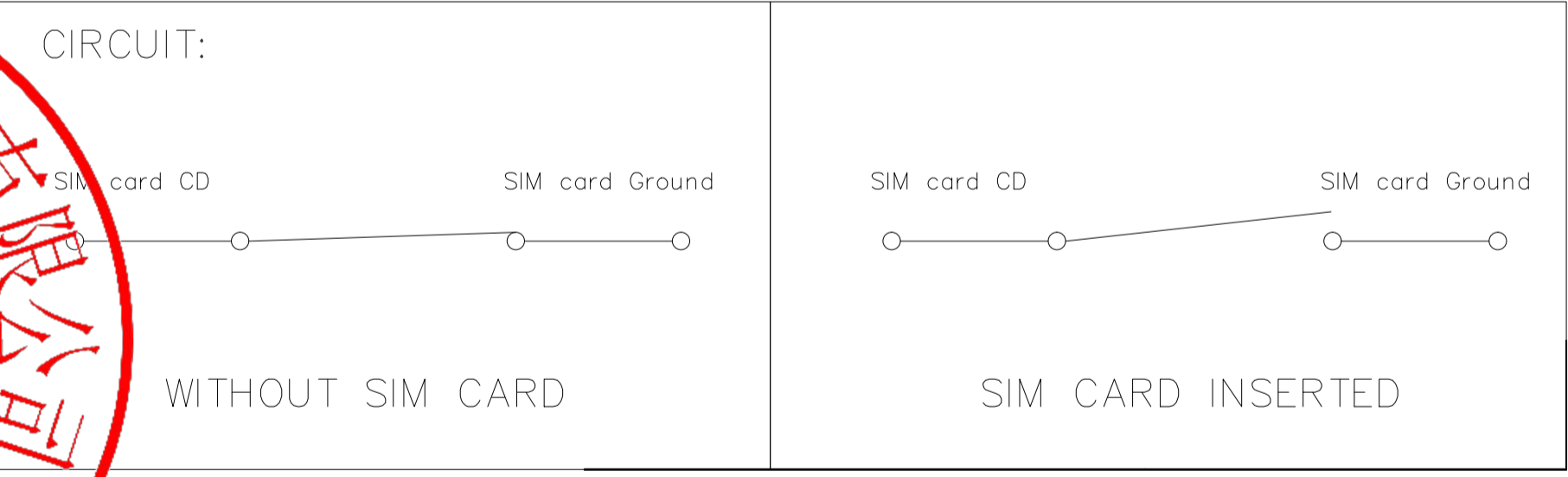
MATERIAL:
Insulator: High Temperature Thermoplastic,
UL 94V-0, COLOR BLACK LCP
(塑胶: 黑色CP, 防火等级UL 94V-0)
Contact: Copper Alloy

PLATING:
Contact: Plated 50u" Ni Overall
Plated Au Selective Contact Area
Plated 100u" Sn Over Ni On Solder Area
(接触端子电镀: 全部镀底50U, 接触区域10U, 焊脚处雾50U/最少)
Shell: Plated 50u" Ni Overall
Plated 1u" Au Selective Contact Area
(外壳电镀: 镀底50U, 焊接处10U)

Electrical:
Current Rating :0.5Amps max(额定电流:0.5A最大)
Voltage Rating :5V AC/DC(额定电压:5V AC/DC)
Ambient Temperature Range :-20° C+60° C(工作温度: -20度到+60度)
Storage Temperature Range :-40° C+70° C(工作环境: -20度到+80度)
Ambient Humidity Range :95% R.H. Max. (上锡效果: 95%以上)
Contact Resistance:100mΩmax. (端子接触电阻: 100mΩ最大)
Insulation Resistance:1000MΩmin./500VDC(绝缘阻抗: 100兆欧最小)
Mating Cycles:5,000 Insertions(寿命: 5000次)
产品耐温温度: 260° C



SIM pin assignment	
PIN#	Name
C1	VCC 电压
C2	RST 重置
C3	CLK 时钟
C4	Reserved 备用
C5	GND 接地
C6	VPP 电压
C7	I/O 输入输出
C8	Reserved 备用



DESIGN	MISS ZENG	SC ALL		未注公差 TOLERANCE		品名: SIM PUSH 8P+1P无柱	
DRAWIGN	MISS LI	ANIT		MM	X.X ±0.25		X.XXX ±0.10
CHECK	Mr. ZENG	SIZE		A4: 210*297	X.XX ±0.15		ANGULAR:±1°
APPROVAL		VERSION		01			

型号:
HH-0111AAAS09A



东莞市航宏电子科技有限公司
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